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Field Device Integration (FDI) - Part 103-1: Profiles - PROFIBUS

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

Obsahuje: EN 62769-103-1:2015, IEC 62769-103-1:2015

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Úrad pre normalizáciu, metrológiu a skúšobníctvo SR, 2015

Podľa zákona č. 264/1999 Z. z. v znení neskorších predpisov sa môžu slovenské technické normy rozmnožovať a rozširovať iba so súhlasom Úradu pre normalizáciu, metrológiu a skúšobníctvo SR.

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EN 62769-103-1

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English Version

Field Device Integration (FDI) - Part 103-1: Profiles - PROFIBUS
(IEC 62769-103-1:2015)

Intégration des appareils de terrain (FDI) - Partie 103-1:
 Profils - PROFIBUS
 (IEC 62769-103-1:2015)

Feldgeräteintegration (FDI) - Profile - Teil 103-1:
 PROFIBUS
 (IEC 62769-103-1:2015)

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CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 65E/354/CDV, future edition 1 of IEC 62769-103-1, prepared by SC 65E "Devices and integration in enterprise systems", of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-103-1:2015.

The following dates are fixed:

- latest date by which the document has to be implemented at (dop) 2016-03-16
national level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with (dow) 2018-06-16
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IEC 61804-3 NOTE Harmonized as EN 61804-3¹⁾ (not modified).

1) To be published.

Annex ZA
(normative)

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with their corresponding European publications**

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NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61784-1	-	Industrial communication networks - Profiles - Part 1: Fieldbus profiles	EN 61784-1	-
IEC 61804	series	Function blocks (FB) for process control - Electronic device description language (EDDL)	EN 61804	series
IEC 62541-100	2015	OPC unified architecture - Part 100: Device Interface	EN 62541-100	2015
IEC 62769-2	-	Field Device Integration (FDI) - Part 2: FDI Client	EN 62769-2 ²⁾	-
IEC 62769-4	-	Field Device Integration (FDI) - Part 4: FDI Packages	EN 62769-4 ²⁾	-
IEC 62769-5	-	Field Device Integration (FDI) - Part 5: FDI Information Model	EN 62769-5 ²⁾	-
IEC 62769-7	-	Field Device Integration (FDI) - Part 7: FDI Communication Devices	EN 62769-7 ²⁾	-

2) To be published.



INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI) –
Partie 103-1: Profils – PROFIBUS**





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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI) –
Partie 103-1: Profils – PROFIBUS**

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CONTENTS

FOREWORD	4
INTRODUCTION	6
1 Scope	7
2 Normative references	7
3 Terms, definitions, abbreviated terms and acronyms	8
3.1 Terms and definitions	8
3.2 Abbreviated terms and acronyms	8
4 Conventions	8
4.1 EDDL syntax	8
4.2 XML syntax	8
4.3 Capitalizations	8
5 Profile for PROFIBUS	9
5.1 General	9
5.2 Catalog profile	9
5.2.1 Protocol support file	9
5.2.2 CommunicationProfile definition	9
5.2.3 Profile device	10
5.2.4 Protocol version information	10
5.3 Associating a Package with a device	11
5.3.1 Device type identification mapping	11
5.3.2 Device type revision mapping	12
5.4 Information Model mapping	13
5.4.1 ProtocolType definition	13
5.4.2 DeviceType mapping	14
5.4.3 FunctionalGroup identification definition	14
5.5 Topology elements	15
5.5.1 ConnectionPoint definition	15
5.5.2 Communication Device definition	17
5.5.3 Communication service provider definition	18
5.5.4 Network definition	18
5.6 Methods	19
5.6.1 Methods for FDI Communication Servers	19
5.6.2 Methods for Gateways	21
Annex A (normative) Topology Scan result schema	28
A.1 General	28
A.2 Network	28
A.3 ProfibusNetworkT	28
A.4 ProfibusConnectionPointT	28
A.5 ProfibusIdentificationT	29
A.6 ProfibusAddressT	30
Annex B (normative) Transfer service parameters	31
B.1 General	31
B.2 sendData	31
B.3 xsreceiveData	31
B.4 xsTransferSendDataT	31

B.5 TransferResultDataT	32
B.6 OperationT	32
Bibliography	33
 Figure 1 – Version mapping problem.....	12
 Table 1 – ProtocolSupportFile for FDI Device Packages	9
Table 2 – ProtocolSupportFile for FDI Communication Packages	9
Table 3 – PROFIBUS CommunicationProfile definition schema.....	10
Table 4 – Catalog values for profile devices.....	10
Table 5 – Version mapping examples.....	11
Table 6 – Device identification information mapping.....	12
Table 7 – Protocol type Profibus_DP	13
Table 8 – Protocol type Profibus_PA.....	14
Table 9 – DeviceType property mapping	14
Table 10 – PROFIBUS Device Types identification attributes	14
Table 11 – ConnectionPoint type for Profibus_DP	15
Table 12 – ConnectionPoint type for Profibus_PA	16
Table 13 – Method Connect arguments	19
Table 14 – Method Disconnect arguments	19
Table 15 – Method Transfer arguments.....	20
Table 16 – Method SetAddress arguments.....	21
Table 17 – Connect service arguments	22
Table 18 – Method Transfer arguments.....	25
Table 19 – Method SetAddress arguments.....	26
Table A.1 – Elements of ProfibusNetworkT	28
Table A.2 – Attributes of ProfibusConnectionPointT	29
Table A.3 – Elements of ProfibusConnectionPointT	29
Table A.4 – Attributes of ProfibusIdentificationT	30
Table B.1 – Attributes of TransferSendDataT	32
Table B.2 – Attributes of TransferResultDataT	32

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/354/CDV	65E/417/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
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FIELD DEVICE INTEGRATION (FDI) –

Part 103-1: Profiles – PROFIBUS

1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-1_CP 3/1 (PROFIBUS DP)¹ and IEC 61784-1_CP3/2 (PROFIBUS PA).

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technical identical to FDI-2022.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 4 IEC 62769-7 is technically identical to FDI-2027.

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD; available at <www.PROFIBUS.com>*

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